

May 1996

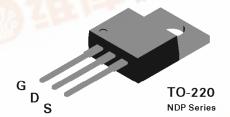
NDP7061 / NDB7061 N-Channel Enhancement Mode Field Effect Transistor

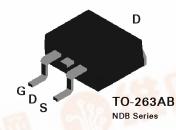
General Description

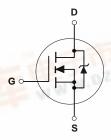
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- 64A, 60V. $R_{\rm DS(ON)}$ = 0.016 Ω @ $V_{\rm GS}$ =10V.
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design for extremely low R_{DS(ON)}.
- TO-220 and TO-263 (D²PAK) package for both through hole and surface mount applications.







Absolute Maximum Ratings

T_c = 25°C unless otherwise noted

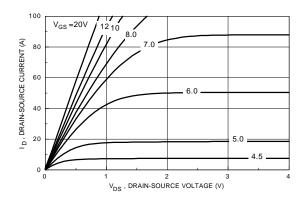
Symbol	Parameter	NDP7061	NDB7061	Units		
V _{DSS}	Drain-Source Voltage		V			
V_{DGR}	Drain-Gate Voltage ($R_{GS} \le 1 \text{ M}\Omega$)		60			
V _{GSS}	Gate-Source Voltage - Continuous	±	±20			
	- Nonrepetitive (t_p < 50 μ s)	A 418:	40			
I _D	Drain Current - Continuous	A178 4 P	64	Α		
	- Pulsed	1	90			
P _D	Maximum Power Dissipation @ T _c = 25°C	1	30	W		
	Derate above 25°C	0	.87	W/°C		
T _J ,T _{STG}	Operating and Storage Temperature Range	-65	to 175	°C		
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	2	275	°C		

Symbol	Parameter	Conditions		Min	Тур	Max	Units
W _{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30 \text{ V}, I_{D} = 64 \text{ A}$				500	mJ
I _{AR}	Maximum Drain-Source Avalanche Curre	ent				64	Α
OFF CH	ARACTERISTICS						-
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		60			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$				10	μΑ
			T _J = 125°C			1	mA
I _{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
	RACTERISTICS (Note 1)	<u>.</u>			•		
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2	2.9	4	V
			T _J = 125°C	1.4	2.2	3.6	
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 35 \text{ A}$	<u>.</u>		0.013	0.016	Ω
			T _J = 125°C		0.021	0.032	
I _{D(on)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$		60			Α
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 35 \text{ A}$			30		S
DYNAMI	C CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$			1930		pF
C _{oss}	Output Capacitance	f = 1.0 MHz			870		pF
C _{rss}	Reverse Transfer Capacitance				310		pF
SWITCH	ING CHARACTERISTICS (Note 1)	-			ı		
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 25 \text{ V}, I_{D} = 64 \text{ A},$			13	30	nS
ţ,	Turn - On Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 5 \Omega$			98	200	nS
t _{D(off)}	Turn - Off Delay Time			36	80	nS	
t _f	Turn - Off Fall Time				65	150	nS
$\overline{Q_g}$	Total Gate Charge	V _{DS} = 48 V,			67	100	nC
$\overline{Q_{gs}}$	Gate-Source Charge	$I_D = 64 \text{ A}, \ V_{GS} = 10 \text{ V}$			11		nC
Q _{gd}	Gate-Drain Charge				37.5		nC

Electrical Characteristics (T _c = 25°C unless otherwise noted)								
Symbol	Parameter	Conditions			Тур	Max	Units	
DRAIN-S	OURCE DIODE CHARACTERISTICS					_		
I _s	Maximum Continuos Drain-Source Diode Forward Current					64	Α	
SM	Maximum Pulsed Drain-Source Diode Forward Current					190	Α	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 35 A (Note 1)			0.9	1.3	V	
		T _J	= 125°C		0.8	1.2		
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_F = 64 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}$		40	105	150	ns	
l _m	Reverse Recovery Current			2	4.5	10	Α	
THERMA	L CHARACTERISTICS		<u> </u>					
R _{øJC}	Thermal Resistance, Junction-to-Case					1.15	°C/W	
R _{øJA}	Thermal Resistance, Junction-to-Ambient					62.5	°C/W	

Note:
1. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%.

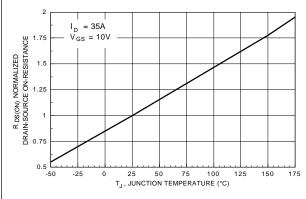
Typical Electrical Characteristics



3 V_{GS} = 5.0V V_G

Figure 1. On-Region Characteristics

Figure 2. On-Resistance Variation with Gate Voltage and Drain Current



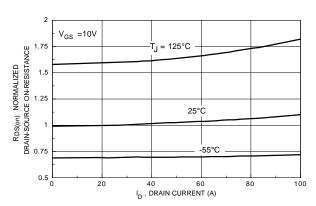
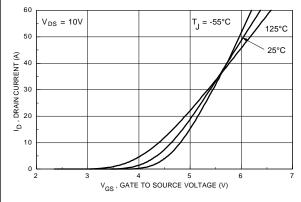


Figure 3. On-Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Drain Current and Temperature



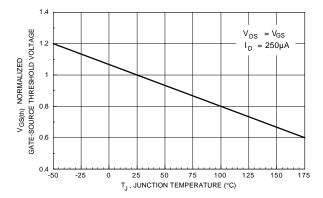


Figure 5. Transfer Characteristics

Figure 6. Gate Threshold Variation with Temperature

Typical Electrical Characteristics (continued)

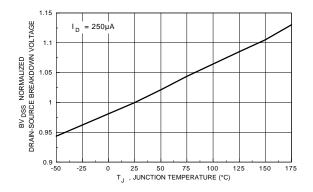


Figure 7. Breakdown Voltage Variation with Temperature

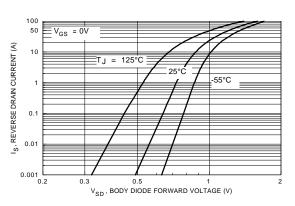


Figure 8. Body Diode Forward Voltage
Variation with Current and Temperature

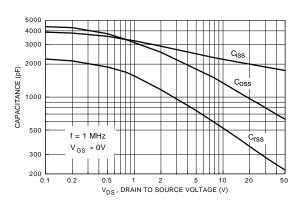


Figure 9. Capacitance Characteristics

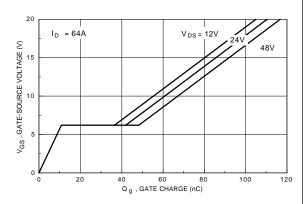


Figure 10. Gate Charge Characteristics

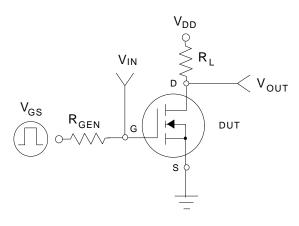


Figure 11. Switching Test Circuit

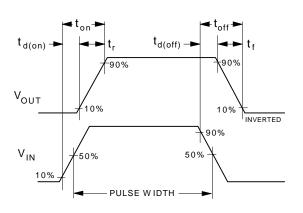
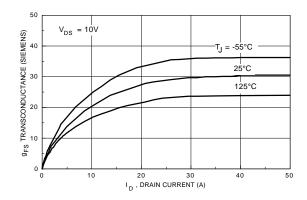


Figure 12. Switching Waveforms

Typical Electrical Characteristics (continued)



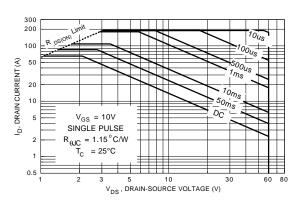


Figure 13. Transconductance Variation with Drain Current and Temperature

Figure 14. Maximum Safe Operating Area

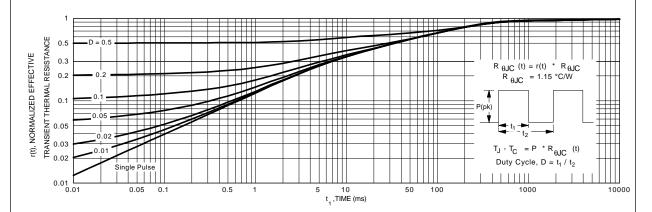
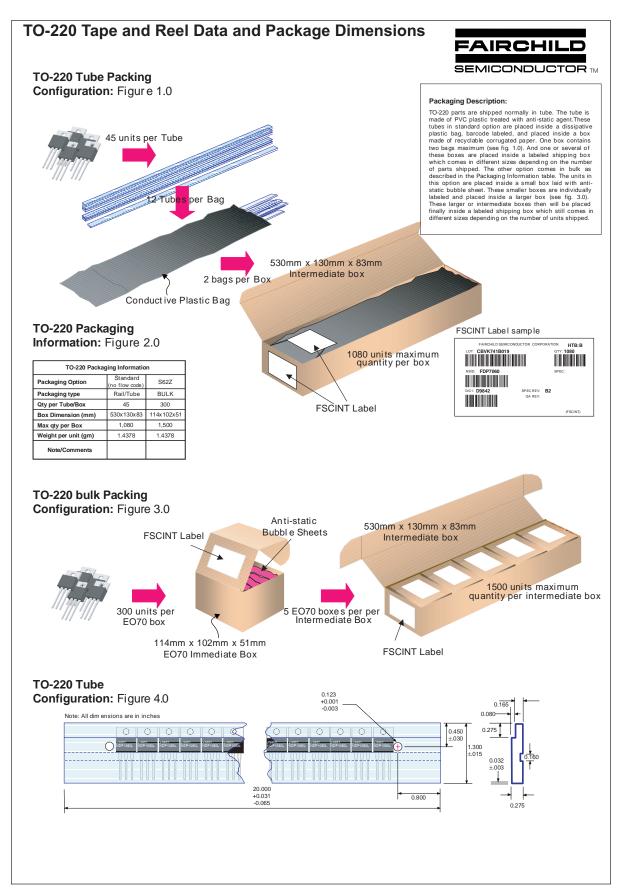
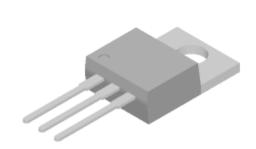


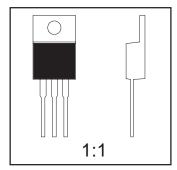
Figure 15. Transient Thermal Response Curve



TO-220 Tape and Reel Data and Package Dimensions, continued

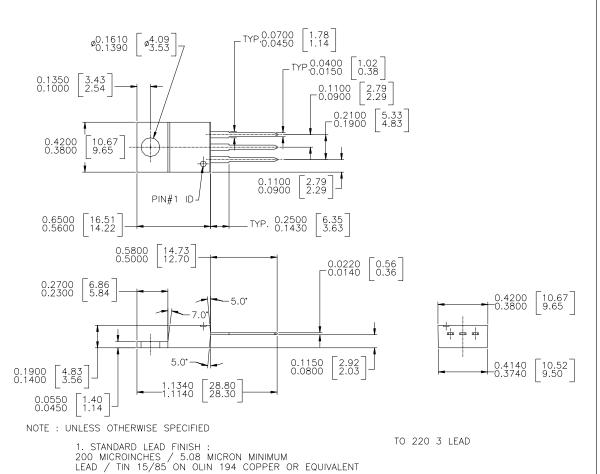
TO-220 (FS PKG Code 37)



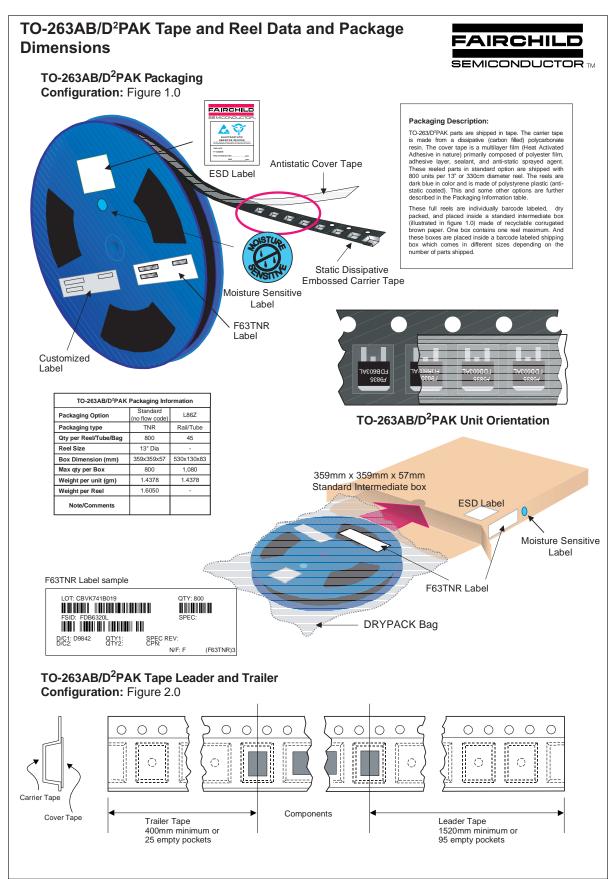


Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 1.4378

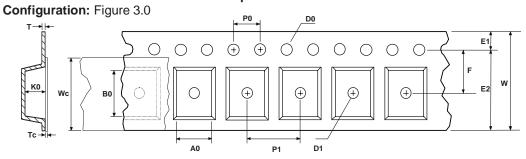


2. DIMENSION BASED ON JEDEC STANDARD TO-220 VARIATION AB, ISSUE J, DATED 3/24/87



TO-263AB/D²PAK Tape and Reel Data and Package Dimensions, continued

TO-263AB/D²PAK Embossed Carrier Tape



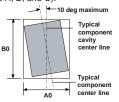
User Direction of Feed

Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
TO263AB/ D ² PAK (24mm)	10.60 +/-0.10	15.80 +/-0.10	24.0 +/-0.3	1.55 +/-0.05	1.60 +/-0.10	1.75 +/-0.10	22.25 min	11.50 +/-0.10	16.0 +/-0.1	4.0 +/-0.1	4.90 +/-0.10	0.450 +/-0.150	21.0 +/-0.3	0.06 +/-0.02

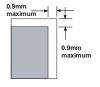
Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

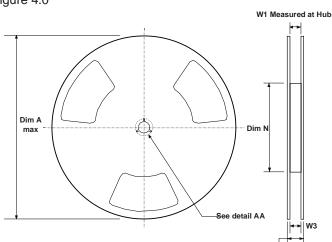


Sketch B (Top View)
Component Rotation

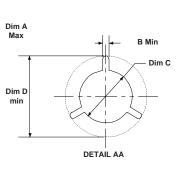


Sketch C (Top View)
Component lateral movement

TO-263AB/D²PAK Reel Configuration: Figure 4.0



13" Diameter Option



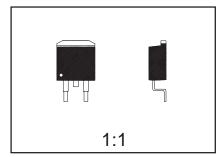
W2 max Measured at Hub

Dimensions are in inches and millimeters Reel Tape Size Dim A Dim B Dim C Dim D Dim N Dim W1 Dim W2 Dim W3 (LSL-USL) Option 512 +0.020/-0.008 13 +0.5/-0.2 0.961 +0.078/-0.000 24.4 +2/0 0.941 - 0.1.079 23.9 - 27.4 0.059 1.5 24mm 13" Dia

TO-263AB/D²PAK Tape and Reel Data and Package Dimensions, continued

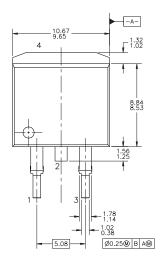
TO-263AB/D²PAK (FS PKG Code 45)

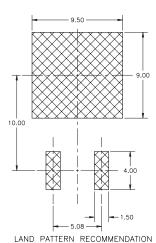


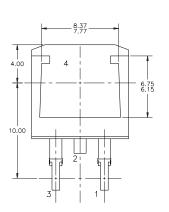


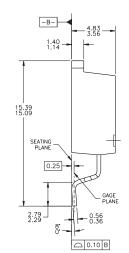
Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 1.4378









- NOTES: UNLESS OTHERWISE SPECIFIED

 A) ALL DIMENSIONS ARE IN MILLIMETERS.
 B) STANDARD LEAD FINISH:
 200 MICROINCHES / 5.08 MICROMETERS MIN.
 LEAD/TIN 15/85 ON OLIN 194 COPPER OR
 EQUIVALENT.
 C) MAXIMUM YERTICAL BURR ON HEATSINK NOT
 TO EXCEED 0.003 INCH / 0.05mm.
 D) NO PACKAGE CHIPS, CRACKS OR SURFACE
 IDENTIFICATION ALLOWED AFTER FORMING.
 E) REFERENCE JEDEC, TO—263, ISSUE C,
 VARIATION AB, DATED 2/92.

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Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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